

Supporting information

## Two Solvent and Temperature Dependent Copper(II) Compounds Formed by a Flexible Ligand: Syntheses, Structures and Properties

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Fig. S1 PXRD patterns of (a) **1** simulated, (b) heating product of **1** in H<sub>2</sub>O/CH<sub>3</sub>CN at 80 °C, (c) heating product of **1** in H<sub>2</sub>O/CH<sub>3</sub>CN at 90 °C, (d) **2** simulated.

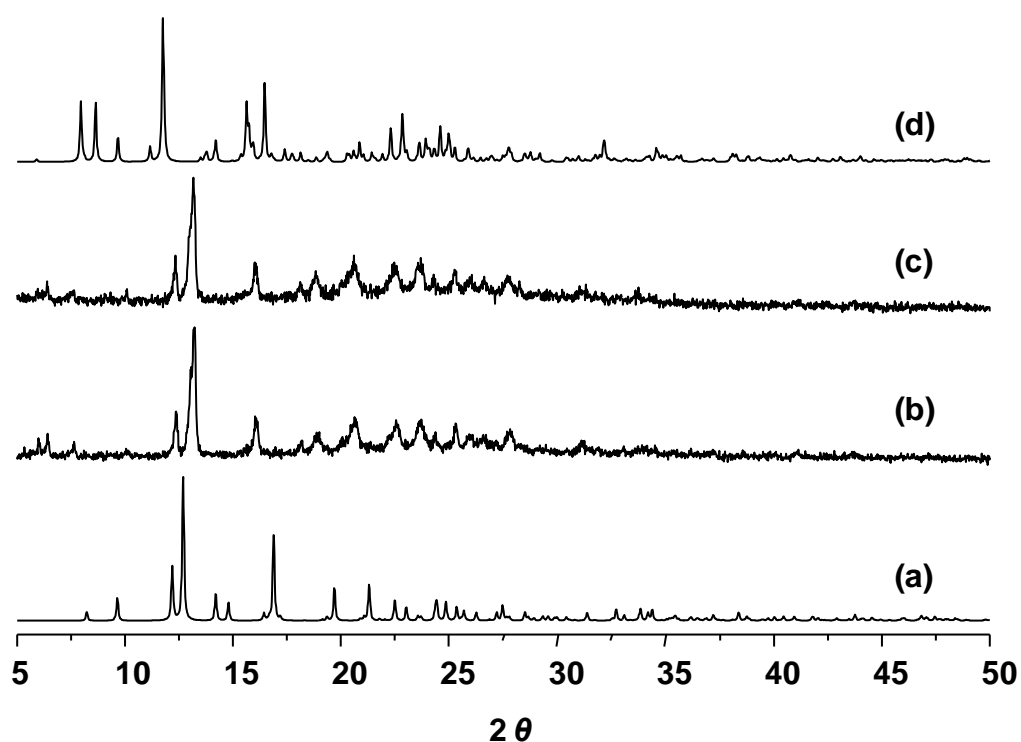


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